



100% Material Declaration Data Sheet SOG20

PK210 (v1.1) June 17, 2011

Average Weight: 0.5607 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.019350	3.451
	Silicon (Si)	7440-21-3	100.00		0.019350	
Die Attach Material					0.003350	0.597
	Resin	Trade Secret	21.00		0.000704	
	Silver (Ag)	7440-22-4	70.00		0.002345	
	Metal oxide	Trade Secret	3.00		0.000101	
	Amine	Trade Secret	3.00		0.000101	
	Gamma Butyrolactone	Trade Secret	3.00		0.000101	
Mold Compound					0.369890	65.971
	Silica Fused	60676-86-0	86.00		0.318105	
	Epoxy Resin (EP)	Trade secret	7.50		0.027742	
	Carbon Black	Trade secret	0.50		0.001849	
	Epoxy Cresol Novolac	29690-82-2	2.00		0.007398	
	Phenol Resin	Trade secret	4.00		0.014796	
Lead Frame					0.161900	28.875
	Copper (Cu)	7440-50-8	97.50		0.157853	
	Iron (Fe)	7439-89-6	2.35		0.003805	
	Phosphorus (P)	7723-14-0	0.03		0.000049	
	Zinc (Zn)	7740-66-6	0.12		0.000194	
Lead Frame Plating					0.001740	0.310
	Silver (Ag)	7440-22-4	100.00		0.001740	
Gold Wire					0.000770	0.137
	Gold (Au)	7440-57-5	99.05		0.000770	
External Plating					0.003690	0.658
	Tin (Sn)	7440-31-5	100.00		0.003690	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
5/20/11	1.0	Initial Xilinx release.
6/17/11	1.1	Update weight of Silica in mold compound

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